



# ***Issues on Segmented Low-Gain Avalanche Detectors (LGAD)***

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with

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# Low-Gain Avalanche Detector (CNM)

Run 6474 2012 (“Pablo”):

Pads 300  $\mu\text{m}$  FZ

Run 6827 2013 (“Marta”):

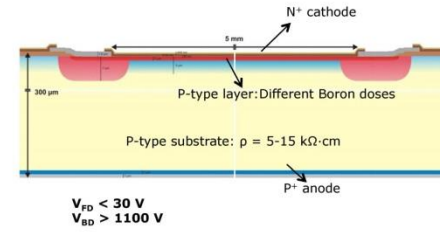
**Pads & Strips & Pixels,  
10-50  $\mu\text{m}$  epi, 300  $\mu\text{m}$  FZ**

Run 7062 2014 (“Virginia”):

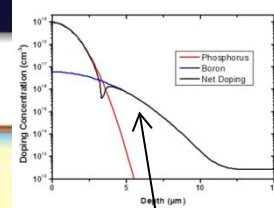
Pads, 300  $\mu\text{m}$  FZ

## Pads detectors with multiplication

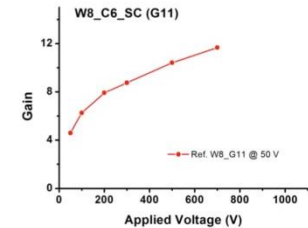
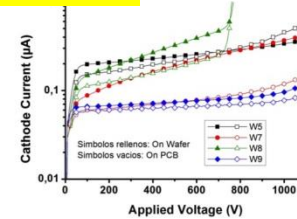
Marta  
Baselga,  
Trento  
Workshop  
Feb. 2013



$V_{FD} < 30 \text{ V}$   
 $V_{BD} > 1100 \text{ V}$



HighField  
: Gain



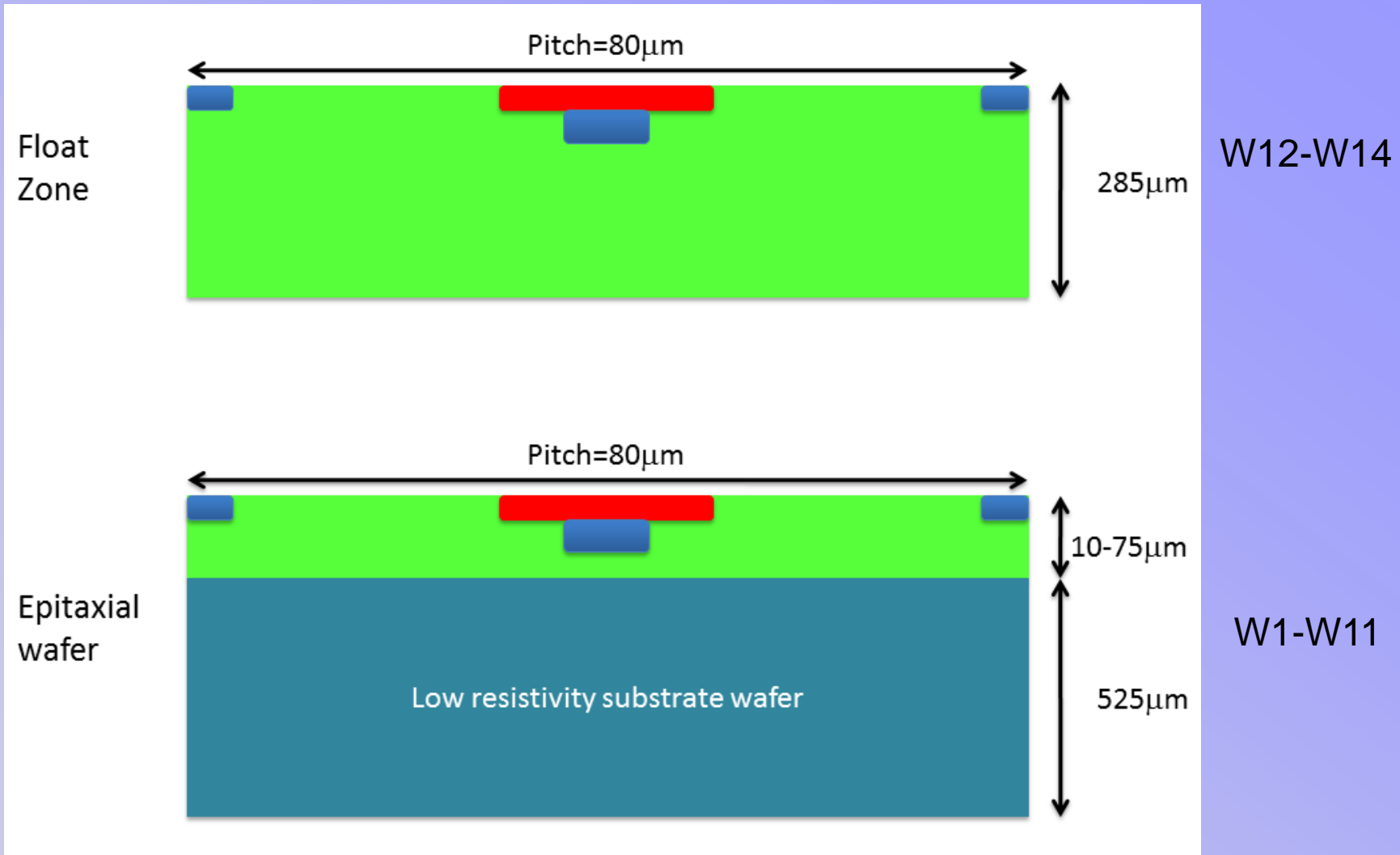
4 / 29

## Question: what do we know about charge multiplication on segmented LGAD?

- Characteristics of Strips from Run 6827
- Gain from TCT
- Doping Concentration from C-V
- Simulations
- Explore Alternative Configurations



# Wafer Options Run 6827



# Run 6827 LGAD Strips

The logo for SCIPP (Stanford University Comprehensive Initiative for Particle Physics) features a stylized evergreen tree above the acronym "SCIPP" in white text on a green rectangular background.

Pitch  $p=80 \mu\text{m}$

	Strip w [ $\mu\text{m}$ ]	Metal [ $\mu\text{m}$ ]	P-implant [ $\mu\text{m}$ ]	w/p	P-implant /pitch
AC1	24	20	6	0.3	7.5%
AC2	24	24	6	0.3	7.5%
AC3	24	28	6	0.3	7.5%
AC4	48	44	30	0.6	37.5%
AC5	48	48	30	0.6	37.5%
AC6	48	52	30	0.6	37.5%
AC7	62	58	44	0.775	55%
AC8	62	62	44	0.775	55%
AC9	62	66	44	0.775	55%
AC10/AC1 1/DC	32	40	14	0.4	17.5%

In addition pixels, and pads with and without gain



# Breakdown Voltages (strips) Run 6827

Wafer	1	4	5	6	8	9	10	11	12	13	14
	Epi	Epi	Epi	Epi	Epi	Epi	Epi	Epi	FZ	FZ	FZ
	10	10	50	50	50	75	75	75	300	300	300
	Sh	St	Sh	St	D	Sh	St	D	Sh	St	D
AC1	5	70	20	60	100	20	5	140	20	200	60
AC2	5	70	25	20	120	25	15	160	20	200	150
AC3	5	10	5	10	160	5	5	110	20	200	150
AC4	5	5	10	10	140	20	5	120	20	140	150
AC5	5	5	5	10	160	20	5	160	20	140	150
AC6	5	5	5	10	160	20	5	150	20	140	60
AC7	5	5	5	10	60	5	5	60	20	80	150
AC8	5	5	5	10	20	5	5	60	20	80	150
AC9	5	5	5	10	40	5	5	60	20	80	150
AC10	5	10	5	10	160	5	5	160	20	5	150
AC11	5	5	5	10	100	20	5	100	20	100	150
FDV					200			450		80	

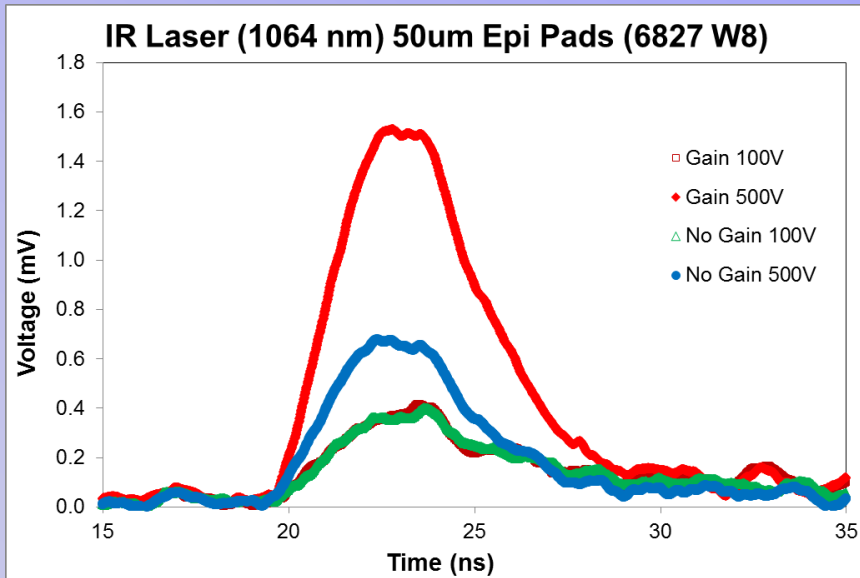
Epi: 100  $\Omega$ -cm, FZ 15 k $\Omega$  -cm

D = Deep implant seems to afford higher break-down voltage, but at same gain?

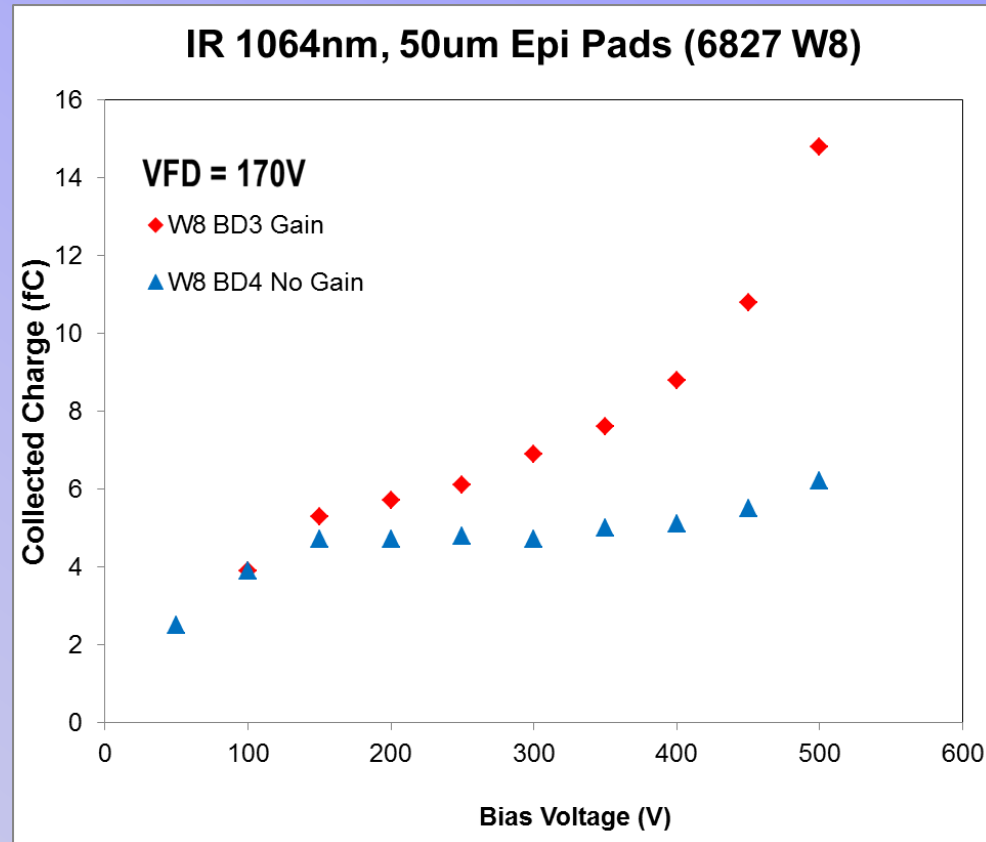
N.B: Break-down voltage of pad sensors > 500V typically



# IR Laser Injection in epi 50 $\mu\text{m}$ pads

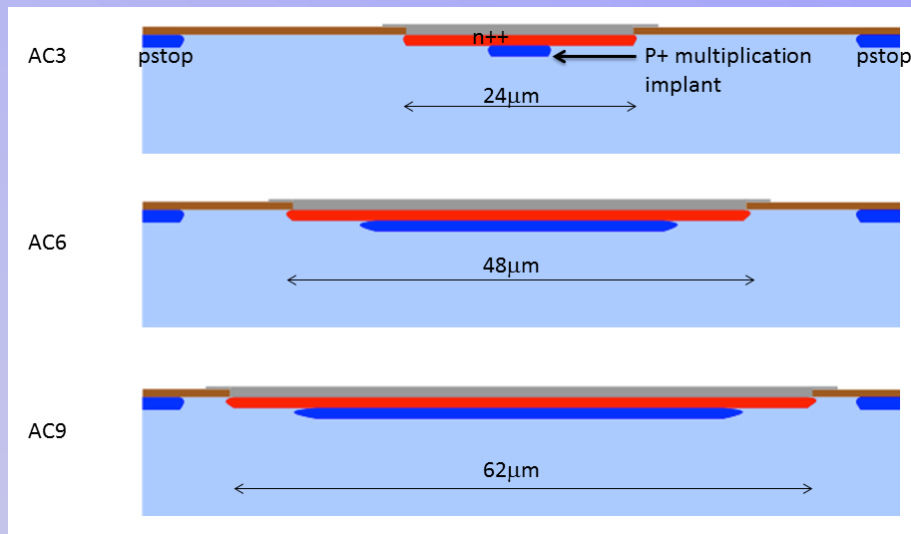


Comparison of LGAD and no-gain pads reveals gain starts at bias of 150V. This is close to the break-down voltage of the strip sensors!





# Issues for 6827 Strip LGAD



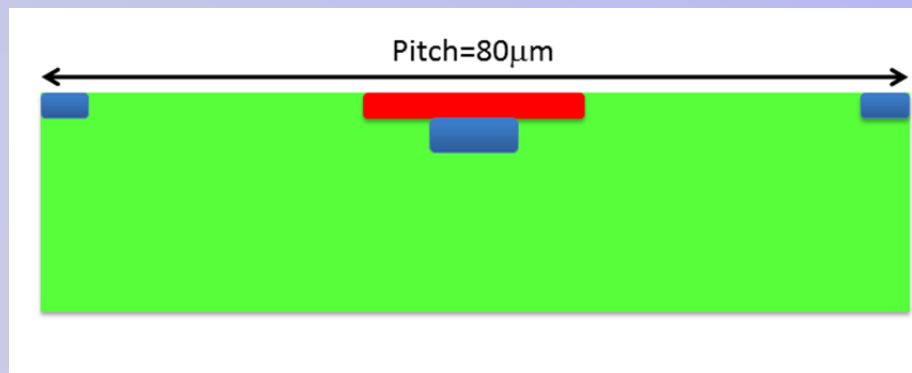
W13 300 µm FZ  
Break-Down  
Voltage [V]

200

140

80

**Issue of field  
at strip edge?**



## Uniformity of Response

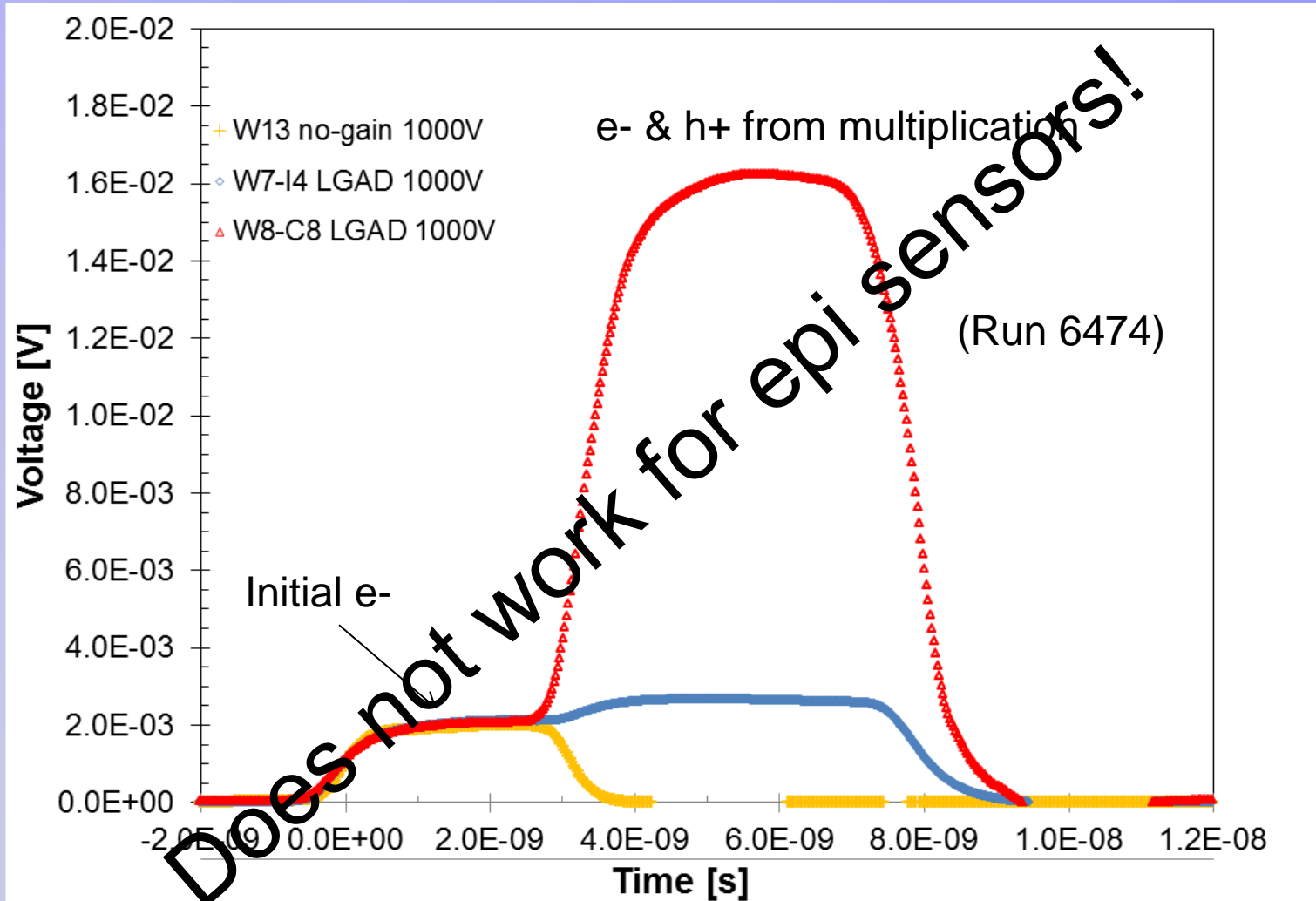
(p-layer covers between 7.5% and 55% of pitch: what fraction of e- are traversing it and are multiplied?)

Simulations

Charge collection



# LGAD Pulse – shape analysis with $\alpha$ TCT



$$\text{Gain} = \text{Total pulse area} / \text{Initial Pulse Area}$$

Gain is characterized by late collection of holes from multiplication

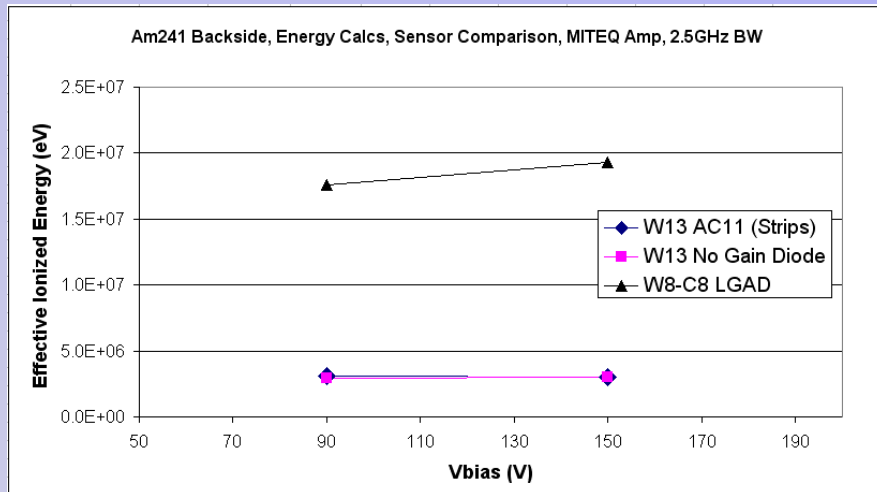
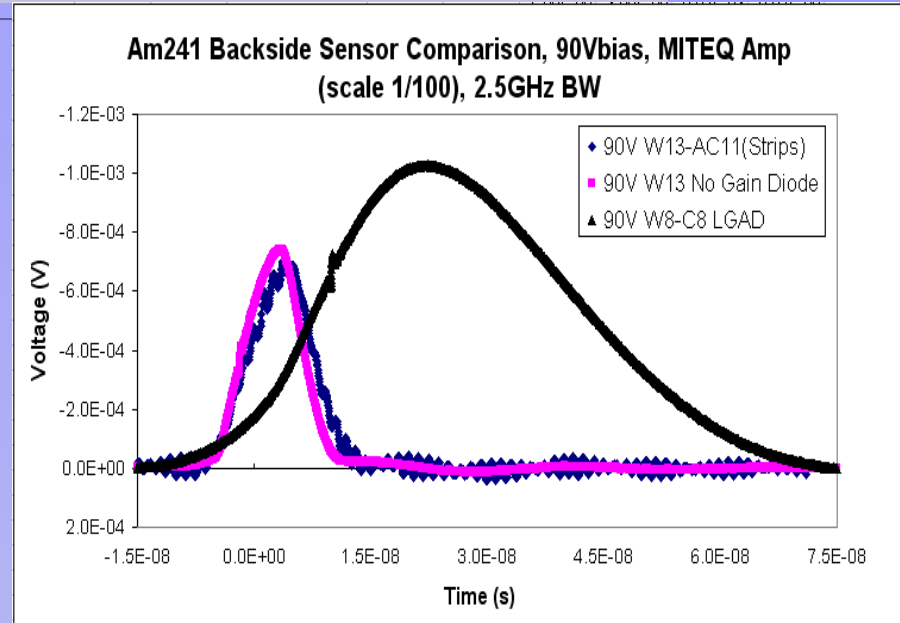


# Sensor Comparison 6474 vs. 6827

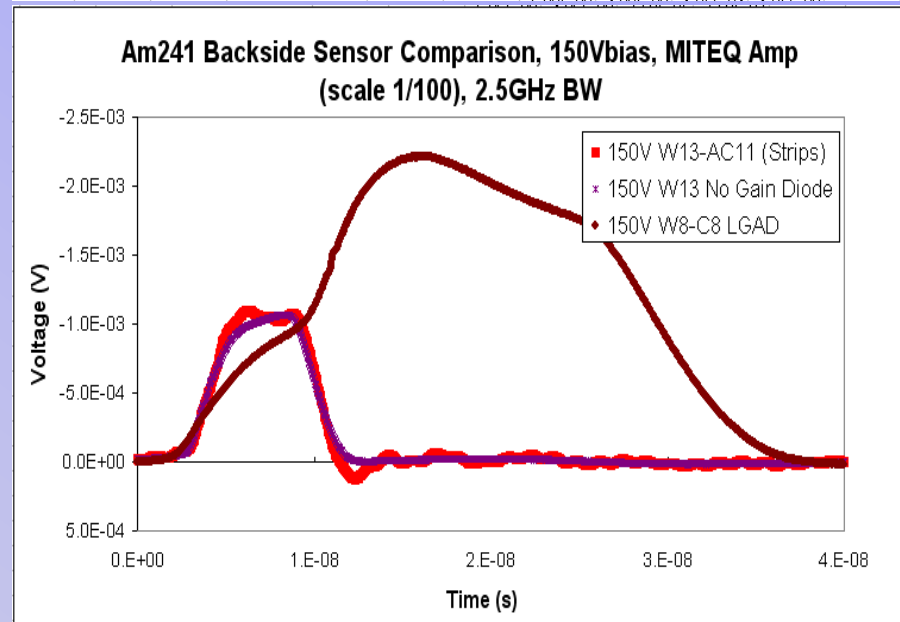


Pulse shapes for 6827-W13 are comparable for no-gain pads and “gain” strip sensor -> No gain observed!

Large difference to LGAD pad (6474-W8 ) which exhibits the characteristic late hole signal.



6474-W8 pulses are huge compared to W13 ones, even at low bias (fields).





# Investigation of the Doping Profile from C-V

(strictly correct only for pad sensors and uniform doping density!!)

Bias Voltage  $V$  – Depleted Region  $x$  : 
$$V = \frac{qN}{2\epsilon\epsilon_0} x^2$$

Resistivity  $\rho$  – Doping density  $N$  : 
$$\rho = \frac{1}{q\mu N}$$

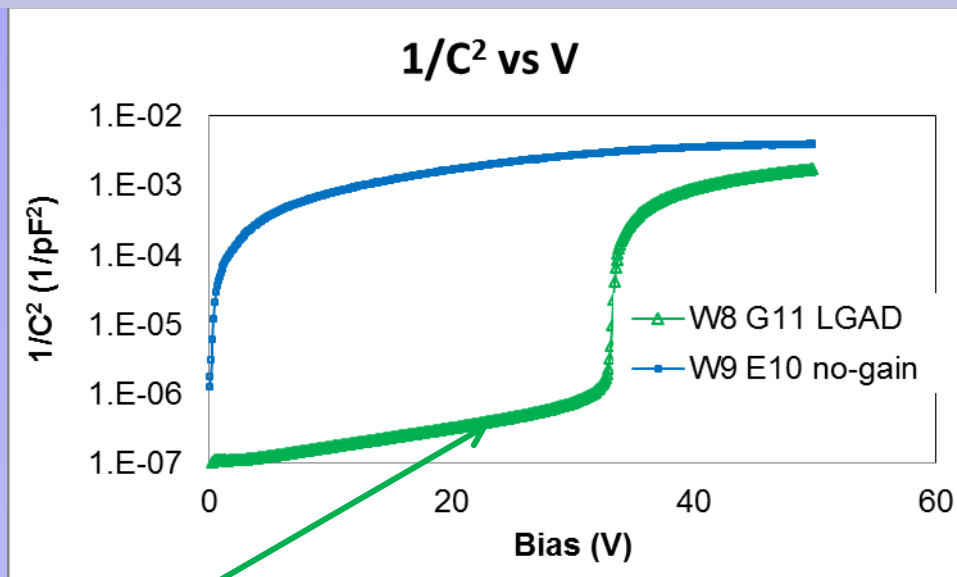
Capacitance  $C$  – Depl. Region  $x$  : 
$$C(x) = \epsilon\epsilon_0 \frac{A}{x} = A\sqrt{\frac{\epsilon\epsilon_0 qN}{2V}}, \Rightarrow x = A / C$$

Doping Density: 
$$N = \frac{2}{\frac{d(1/C^2)}{dV}} \cdot \frac{1}{\epsilon\epsilon_0 q A^2} = \frac{2}{\frac{d(1/C^2)}{dV}} \cdot \frac{1}{1.6 \cdot 10^{-7} A^2}$$

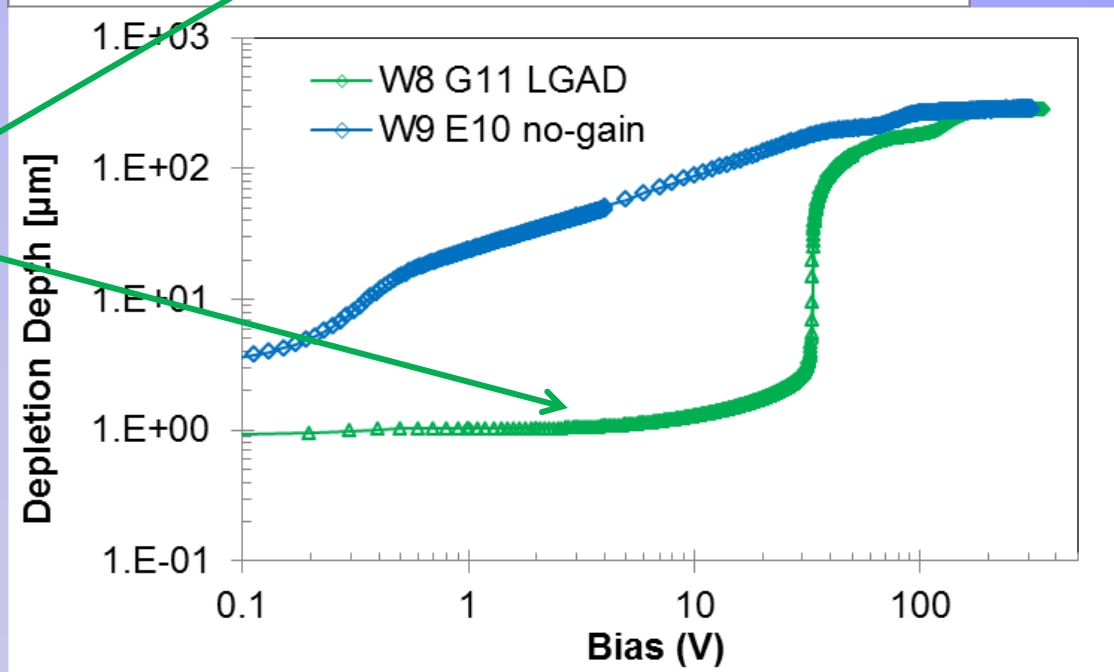


# Large C-V Difference LGAD/no-gain at low Bias

Run 6474  
Example on pads  
W8G11: LGAD  
W9E10 no-gain



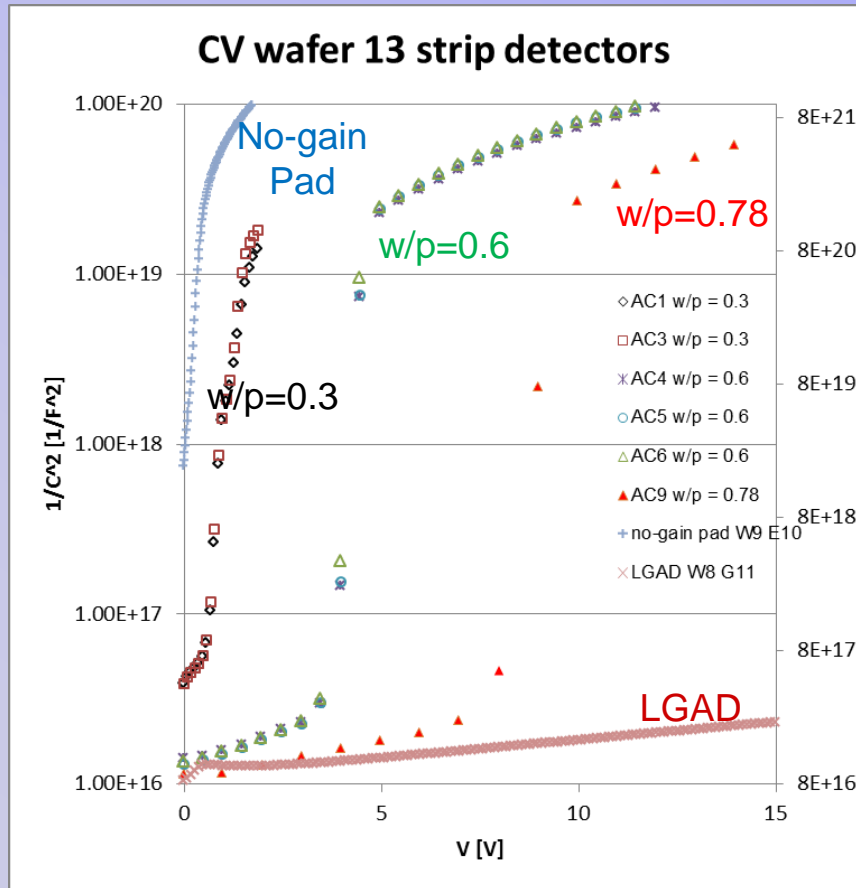
Important:  
Take voltage steps  
of 0.1V below 50 V  
(below the “foot” / “lag”).



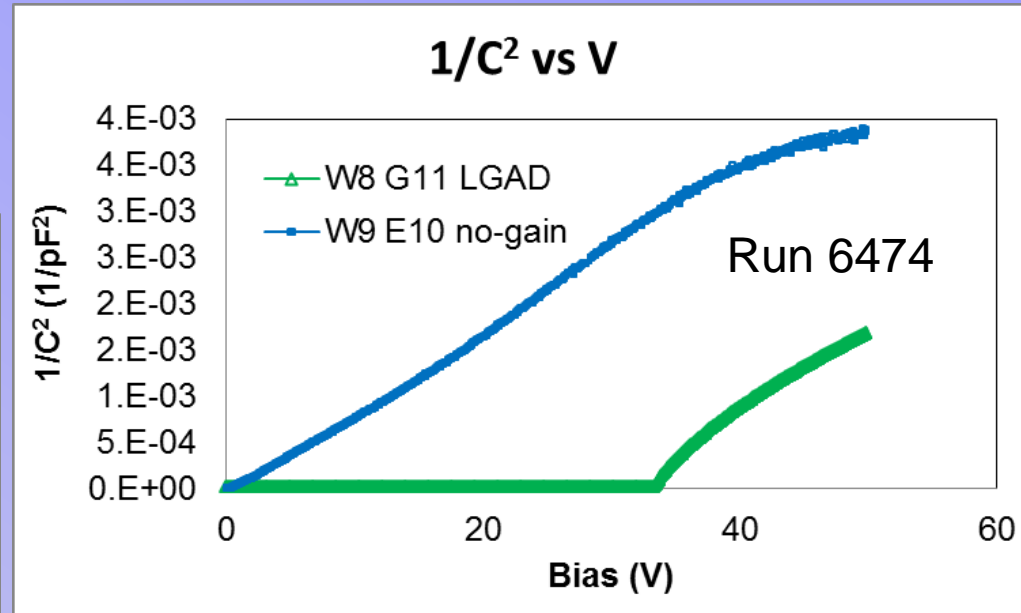
# Large Voltage “Lag” due to Strip Geometry



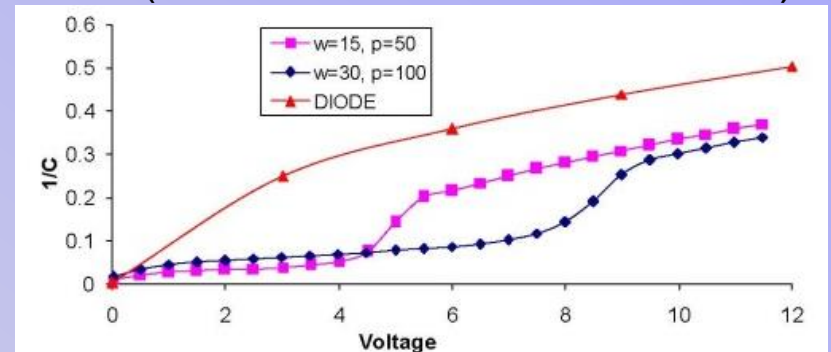
Careful: “foot” indicates gain only with pads!  
 FZ **strips** gain?/no-gain?



Example of “Foot” on pads

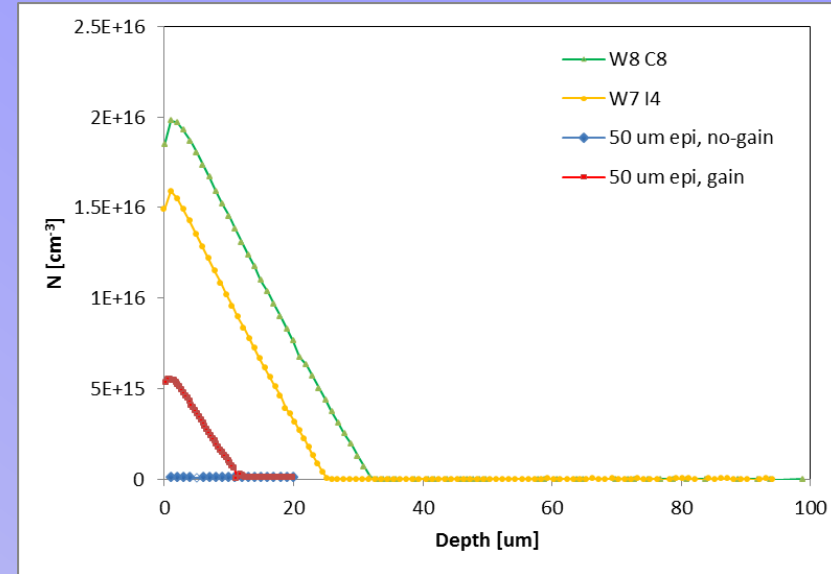
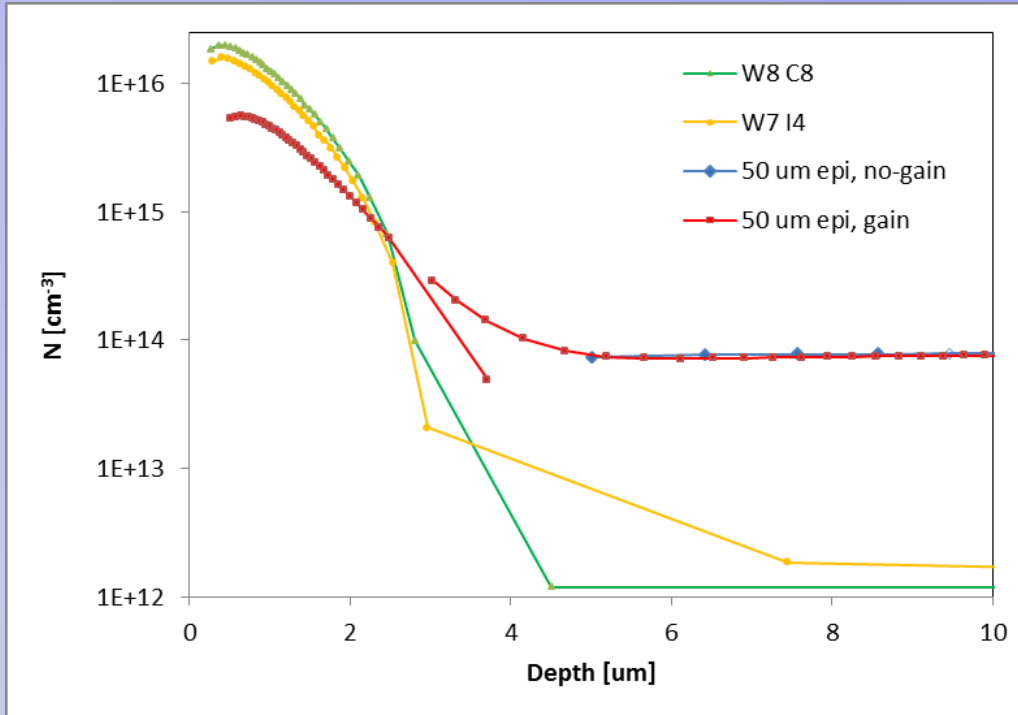


Example of “Foot” in no-gain SMART FZ strips due to lateral depletion (Chris Betancourt M.S. Thesis)





# Doping Density Profile

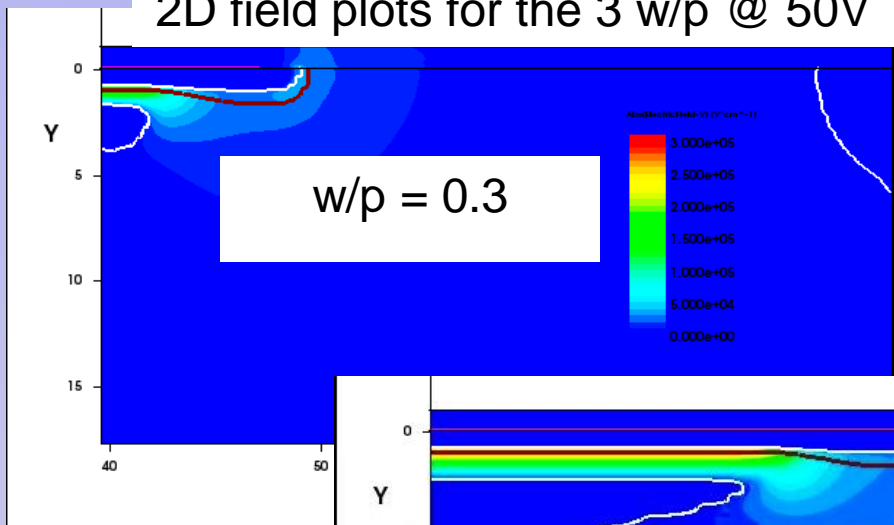


Device	Voltage Lag [V]	$N_{\max}$ [ $\text{cm}^{-3}$ ]	$N_{\text{Bulk}}$ [ $\text{cm}^{-3}$ ]	Gain (400V)
W8 C8 FZ (6474)	35	$2.0 \times 10^{16}$	$1.6 \times 10^{12}$	8
W7 I4 FZ (6474)	29	$1.6 \times 10^{16}$	$1.6 \times 10^{12}$	2.5
50um epi (gain)	14	$0.6 \times 10^{16}$	$7 \times 10^{13}$	$\sim 1.7$
50um epi (no-gain)	< 1	$7 \times 10^{13}$	$7 \times 10^{13}$	1

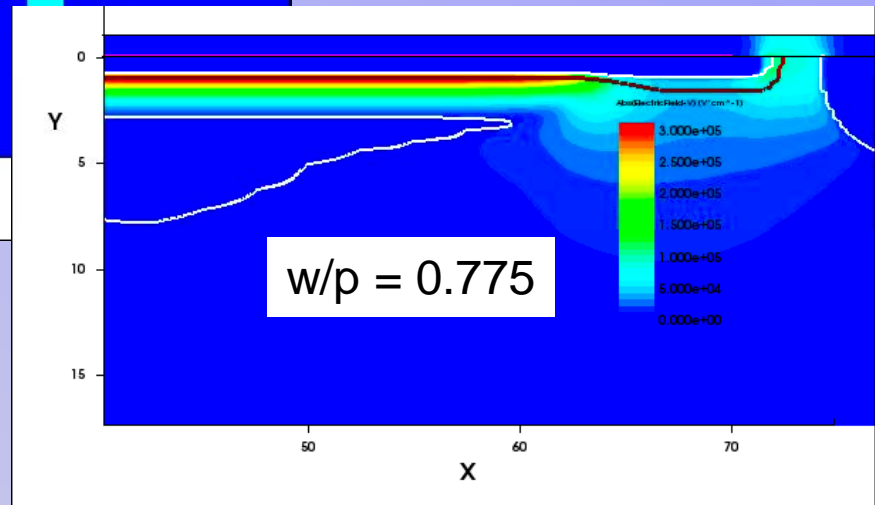
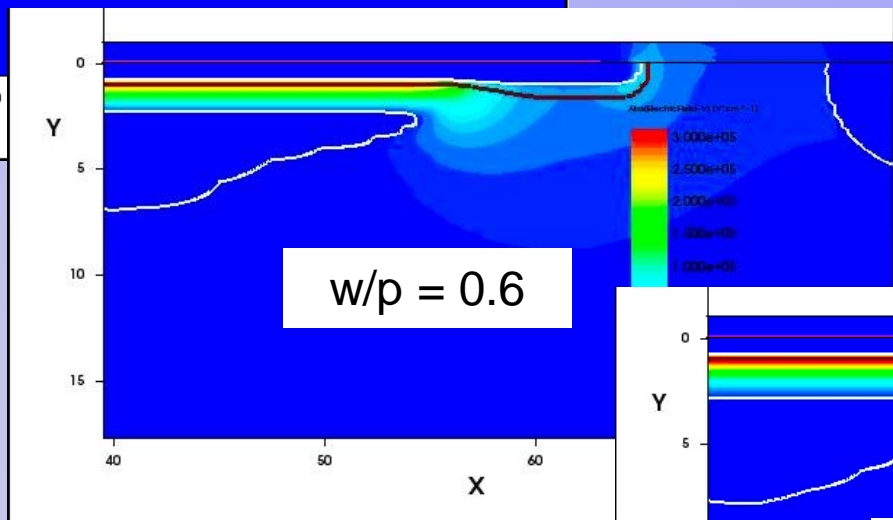
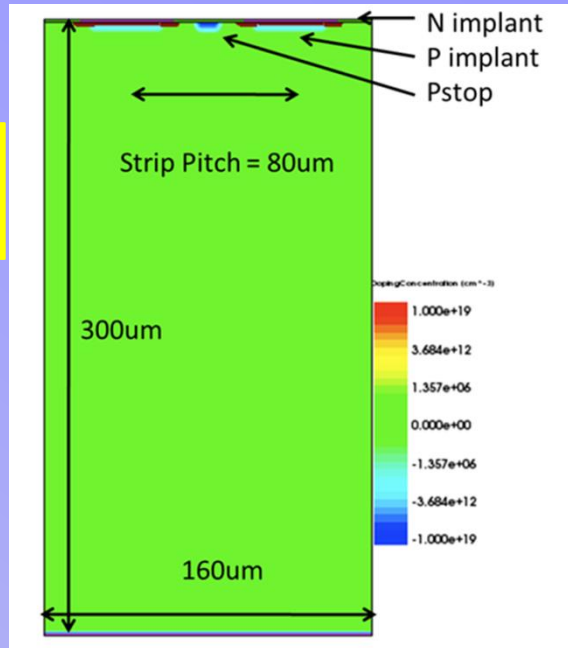


# 2D Field Simulation -> Gain Uniformity

2D field plots for the 3 w/p @ 50V



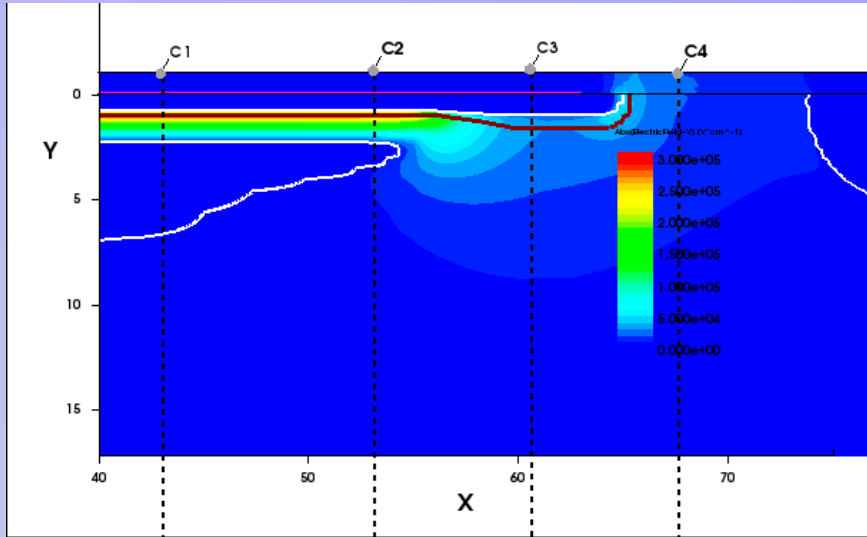
Marta Baselga & Colin Parker



More gain coverage appears for larger  $w/p$ , outside of implant area no large field extension.

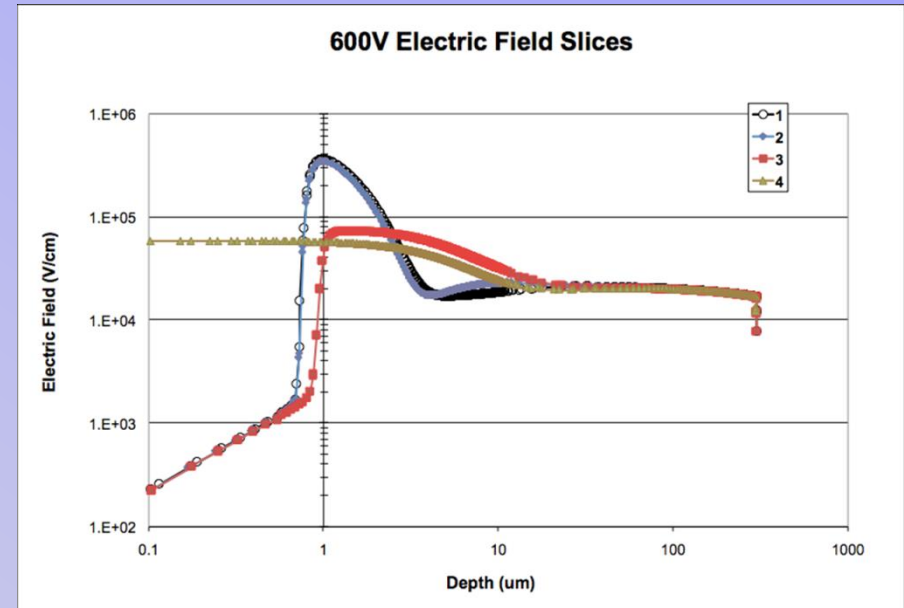
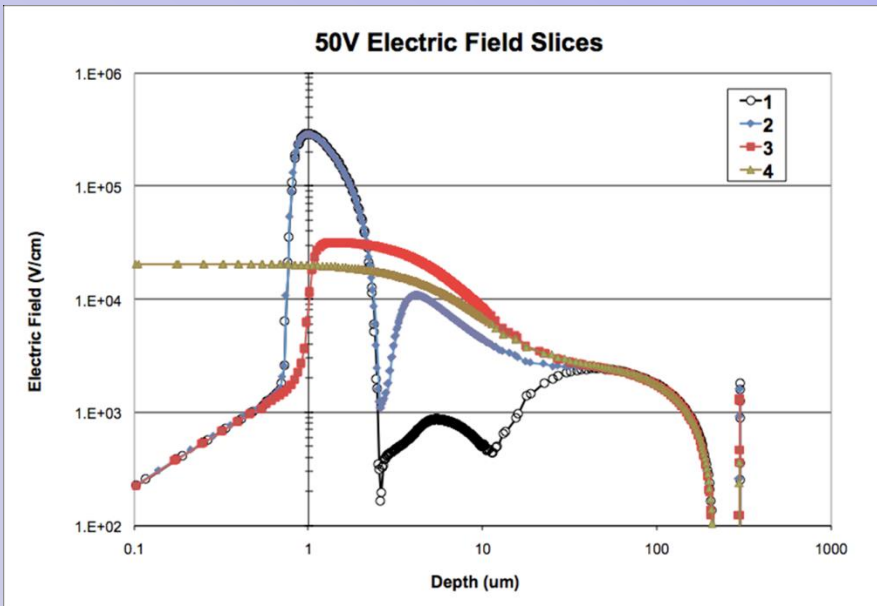


# Field Slices for $w/p = 0.6$



Electric field magnitude along 4 slices show large differences in the electric field across the pitch, suggesting also large difference in gain in those areas.

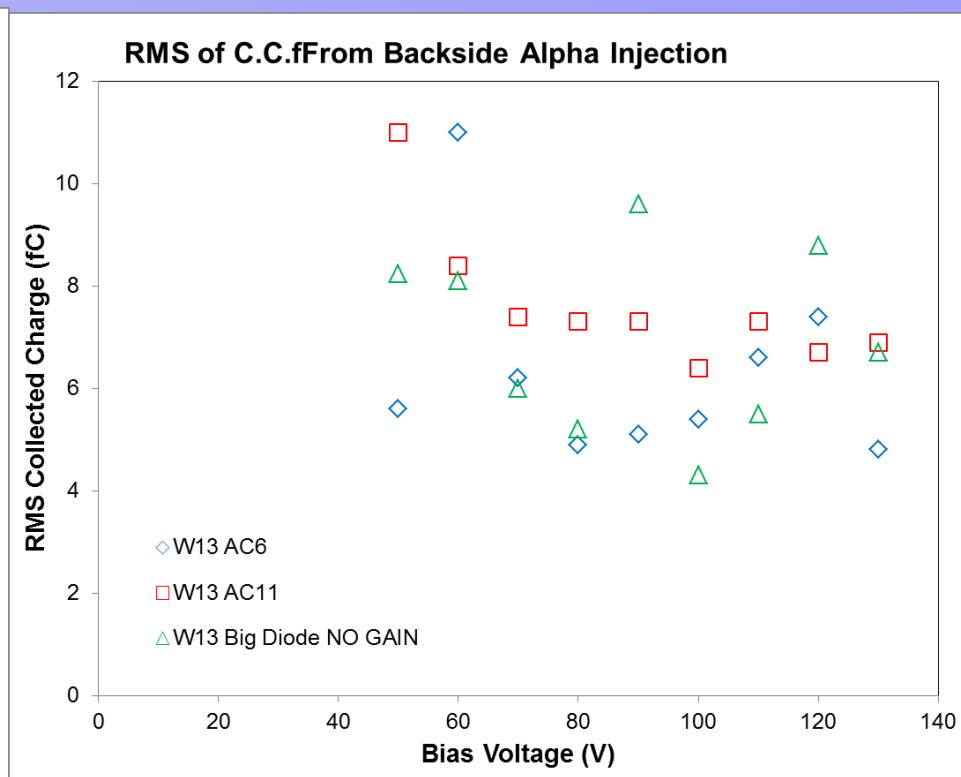
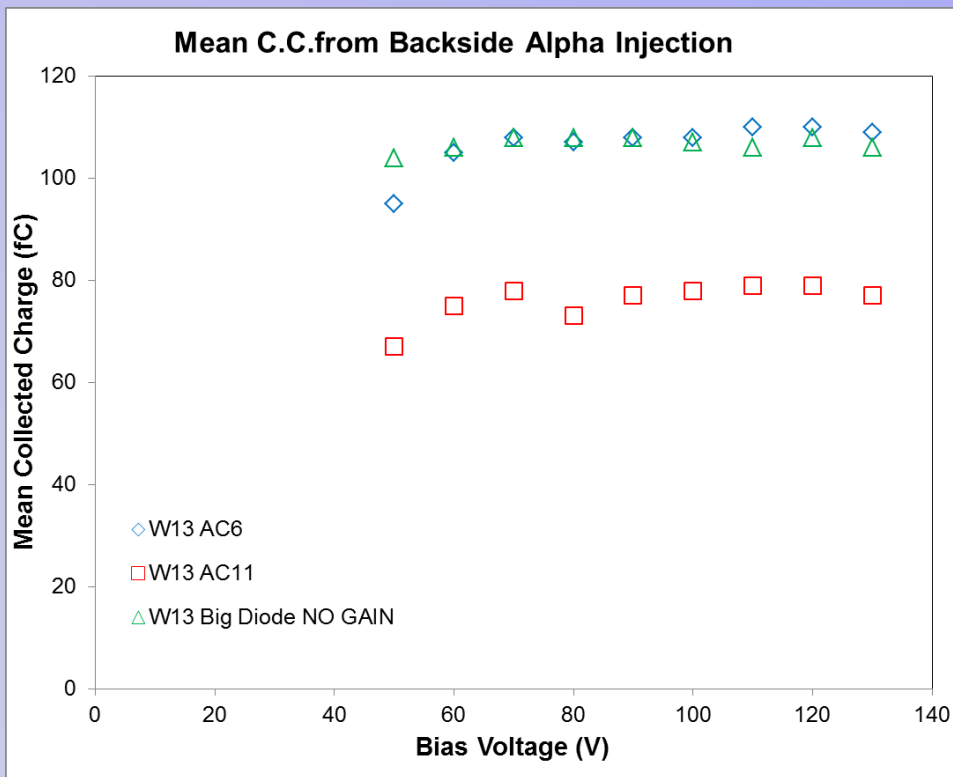
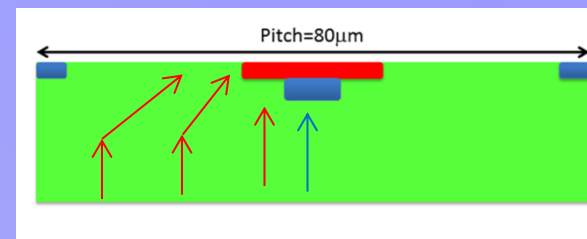
Marta and Colin are working on extracting the 2D field map to predict the electric field vectors and the charge multiplication along different electron paths (to be merged with "Weightfield").





# Two types of pulses: gain/no-gain?

Partial coverage of the strip with the p+ multiplication layer should lead to two distinct pulse shapes:  
Turn-on of multiplication with bias should increase both the mean and the RMS of the collected charge.

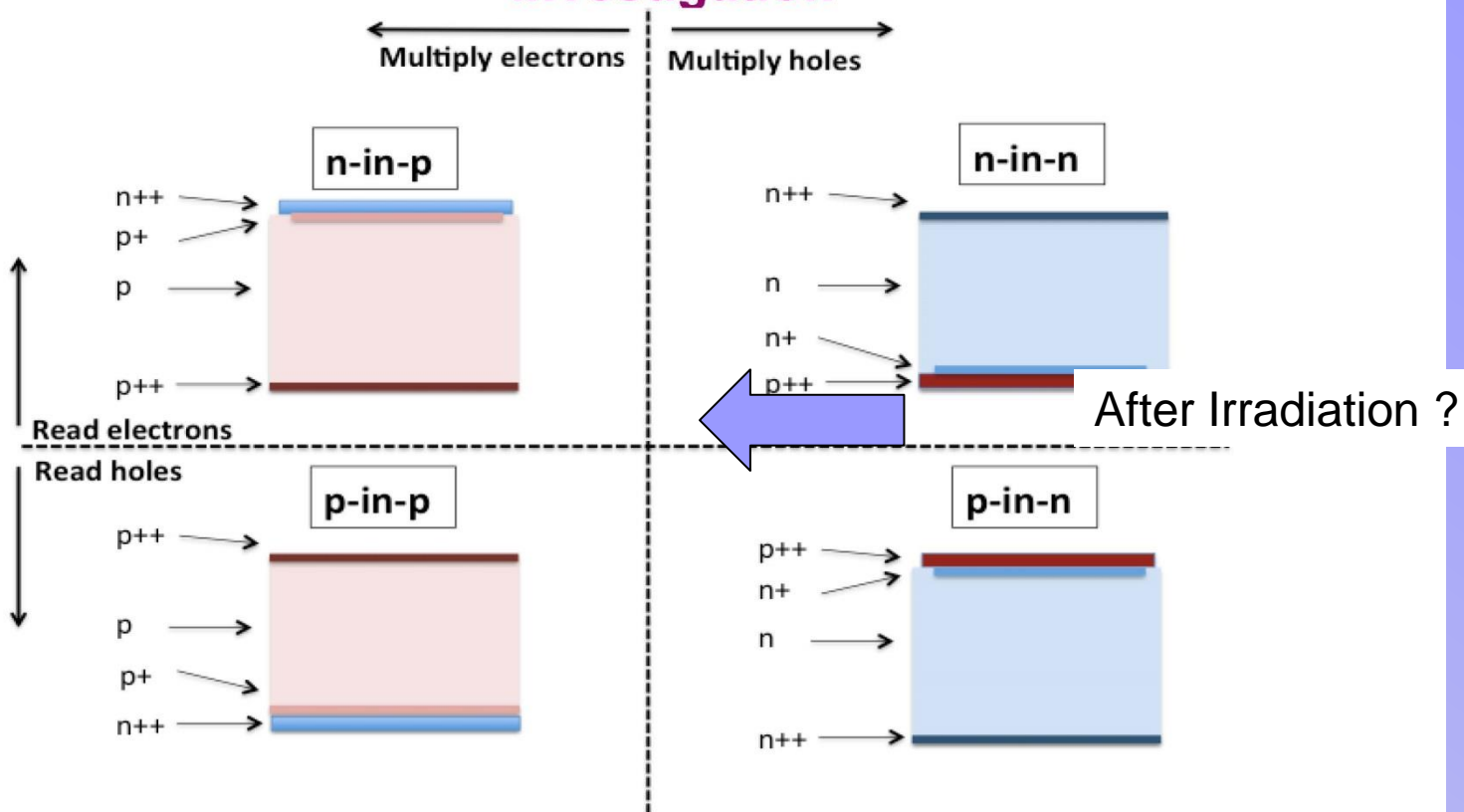


No increase in pulse mean and RMS observed for strips: no observable gain before breakdown.



## New directions

### New designs for the gain layer position/doping under investigation





# Pulse Simulations with “Weightfield”

## Pulse shapes for the 4 types of sensors with gain

**4 sensor types:** n & p bulk and n & p strip implants.

**Combine two things which are proven to work:**

**Gain** is always on an **non-segmented p-n junction** (like LGAD pads)

**Charge collection** is on the **segmented ohmic side** (like n-on-n strips)

Use **Weightfield** 2.1 settings, MIP  
3 strips, pitch = 80  $\mu\text{m}$ , width 30  $\mu\text{m}$   
“gain” = 2 and 3, h/e = 0.03  
Scope BW = 2.5 GHz (black curves)

Developed by  
Nicolo Cartiglia.

Need to merge it with  
2D field simulations.

Thickness

30  $\mu\text{m}$ : bias = 100, 150V, VFD = 20V

50  $\mu\text{m}$ : bias = 200, VFD = 30V

300  $\mu\text{m}$ : bias = 1000, VFD = 80V

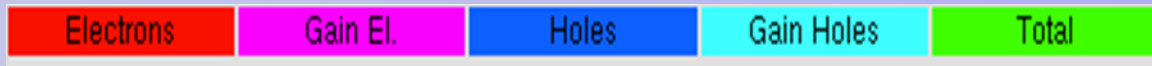
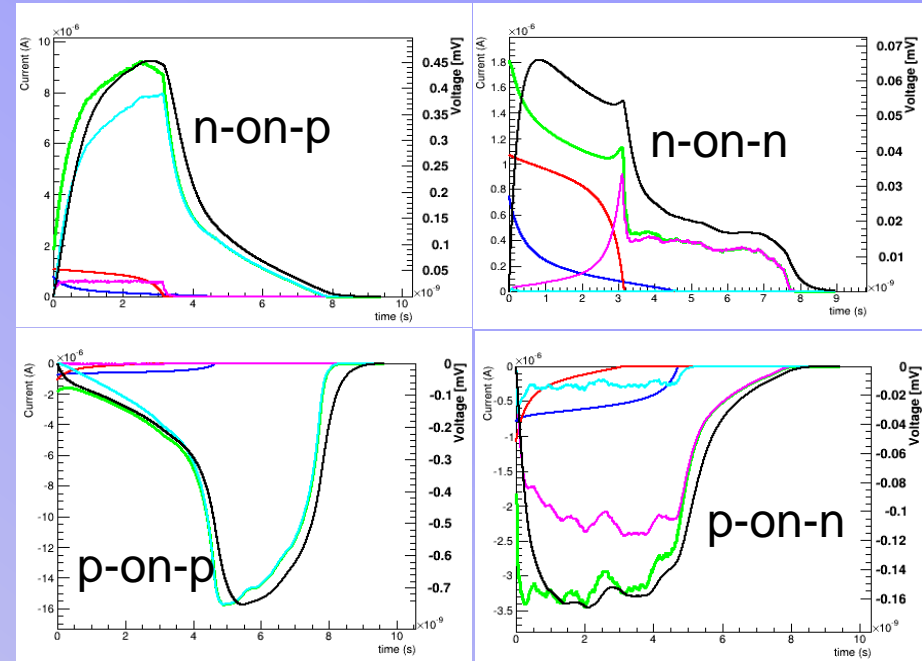
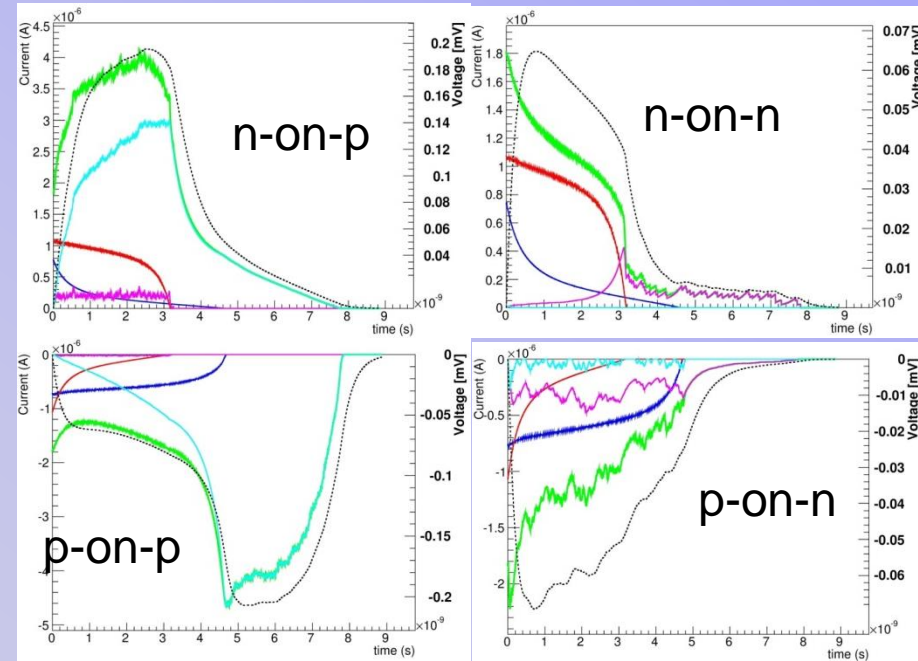
**Investigate the relation between gain and slew rate for timing.**



# Pulse shapes for MIP in 300 $\mu\text{m}$ LGAD

gain = "2"

gain = "3"

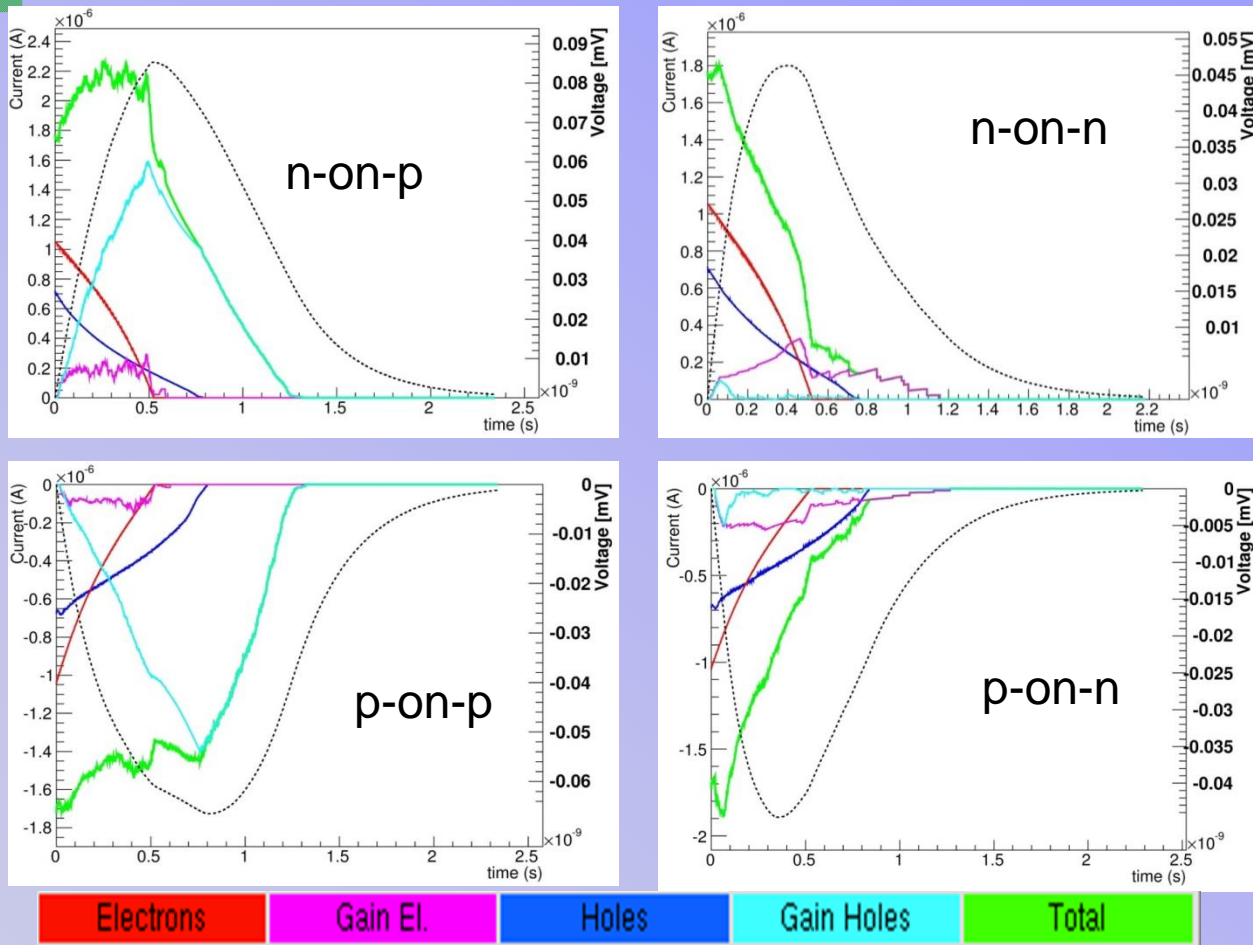


**Thick p-type LGAD rely on late hole collection: p-on-p not viable.  
Thick n-type LGAD rely on much smaller hole multiplication  
(with a fast p-on-n).**



# Pulse shapes for MIP in 50 $\mu\text{m}$ LGAD

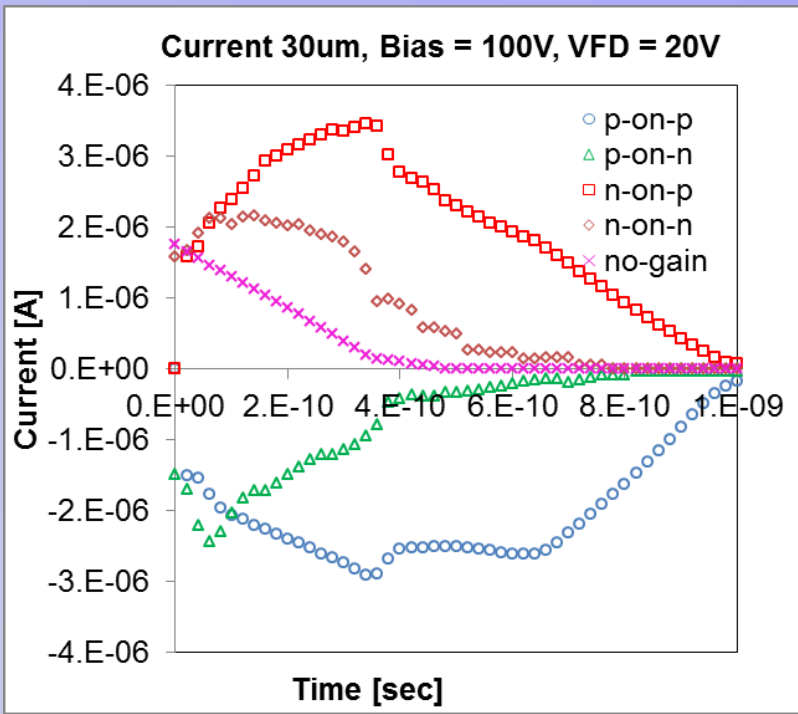
**Bias = 200 V**  
**VFD = 30 V**



**The no-gain pulse (sum of red and dark blue) is very fast.**  
**A thin LGAD needs a fair amount of gain to improve on the fast no-gain pulse!**  
**Thin p-on-p LGAD might be viable, although the holes are more delayed than in n-on-p.**



# Slew Rate $dQ/dt$ is F.o.M. for Time Resolution



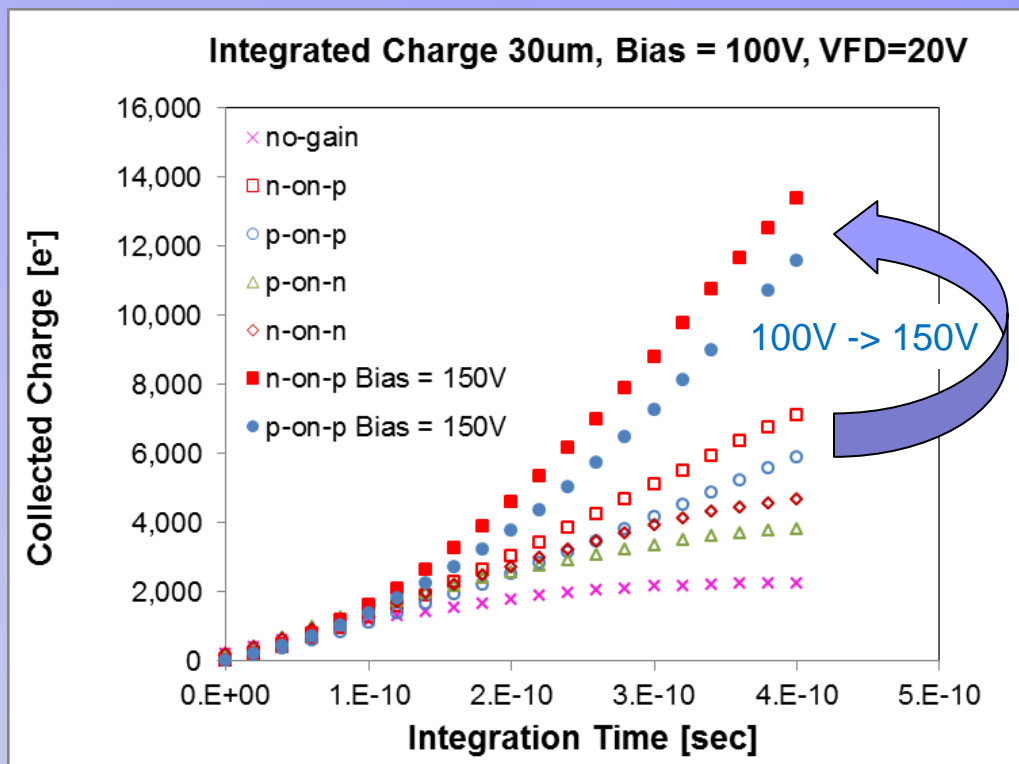
Thin p-on-p LGADs look viable, especially with large gain:

**Charge [ $ke^-$ ] within 400ps:**

Bias:	100V	150V
p-on-p	5.9	11.6
n-on-p	7.1k	13.4
n-on-n	2.3 (no-gain)	

**Gain:**

Bias:	100V	150V
n-on-n	2.3	
p-on-n	1.9	
p-on-p	5.5	11.5
n-on-p	5.2	10.5





# Conclusions from Run 6827

- Segmented sensors from Run 6827 show very low gain attributable to low doping density of the p-implant layer and the low breakdown voltages.
- The important question how uniform the response is (i.e. how much the gain differs for electrons arriving at different regions of the strip) could therefore not be answered. We need a simulation program to estimate this information using 2D simulations, taking into account the doping profile.
- Scans across the strips of “Spaghetti” diodes implemented in the next run are expected to allow answering this question on a variety of strip geometries.
- To achieve uniformity of response and high bias operation in thin segmented sensors, a spatial separation of the charge collection and the gain mechanism combines two aspects which have proven to work at high bias voltage:
  - a) LGAD pads and b) strips on the ohmic side.
- Simulations with “Weightfield” indicate that for very thin sensors, i.e. very fast charge collection, p-on-p is a viable option.
- Since most of the signal from charge multiplication is late, a large gain ( $>10$ ) is needed for fast collection in thin sensors.



# Acknowledgements

Part of this work has been performed in the framework of the CERN RD-50 collaboration and (partially) financed by the Spanish Ministry of Education and Science through the Particle Physics National Program (FPA2010-22060-C02-02 and FPA2010-22163\_C02-02).

Marta Baselga acknowledges a stipend from the Spanish Ministry of Science and Innovation (FPA2010-22060-C02-02).

This research was carried out with the contribution of the Ministero degli Affari Esteri, “Direzione Generale per la Promozione del Sistema Paese” of Italy.

The work at SCIPP was partially supported by the United States Department of Energy, grant DE-FG02-04ER41286.

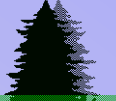


# Back-up

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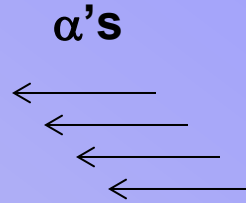
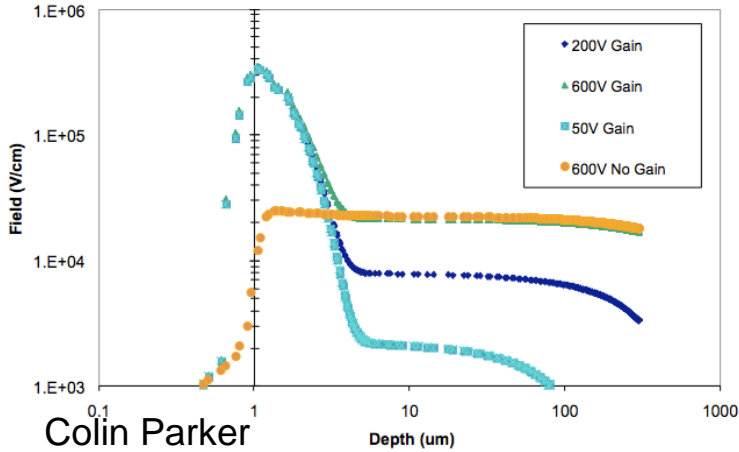


# Charge Collection with $\alpha$ 's from Am(241)

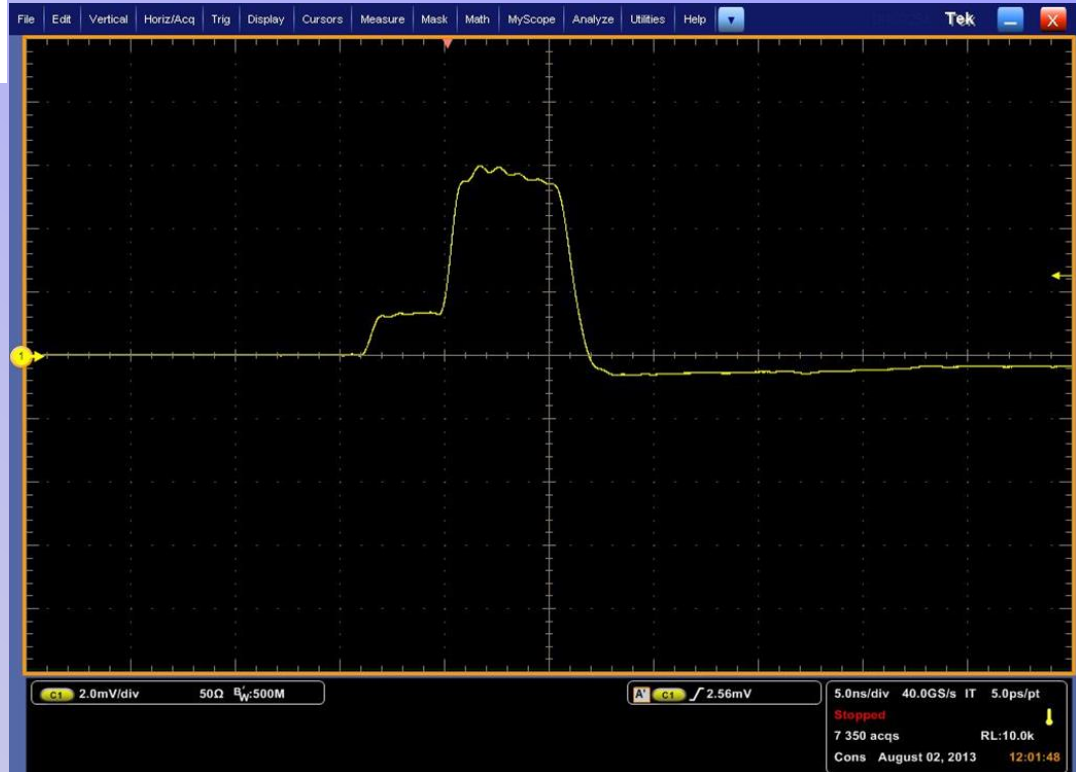


SCIPP

Electric Field vs. Depth



**Am(241)**  
illuminating the back side,  
range ~ few um's  
"electron injection"  
signal drifts and is then  
amplified in high field



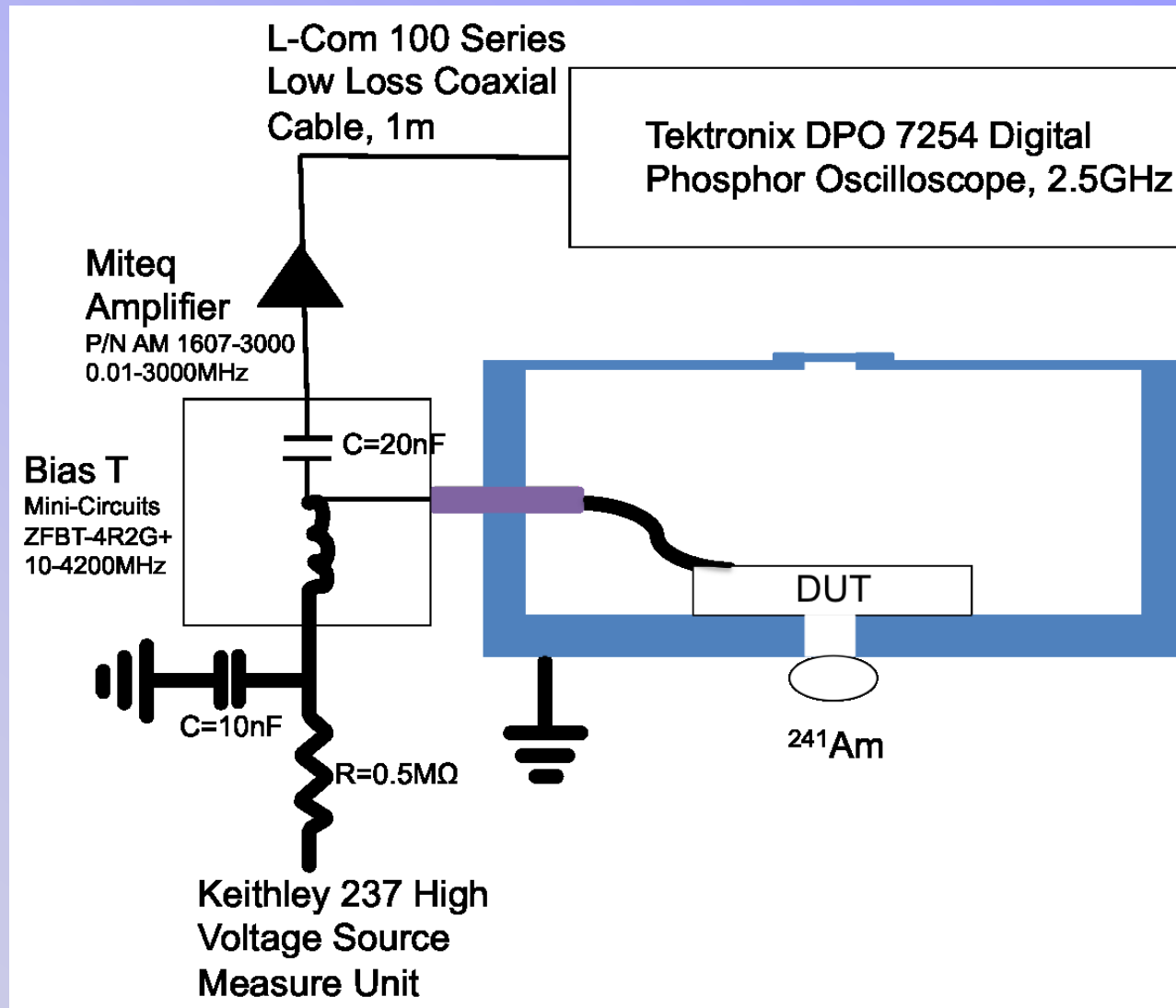
**Fast signals!**

Observed rise times  $\approx 400$  ps  
allowing time-resolved current  
transient (TCT) analysis .

Don't know yet where the  
lower limit is, since we are still  
improving the BW of the  
system.

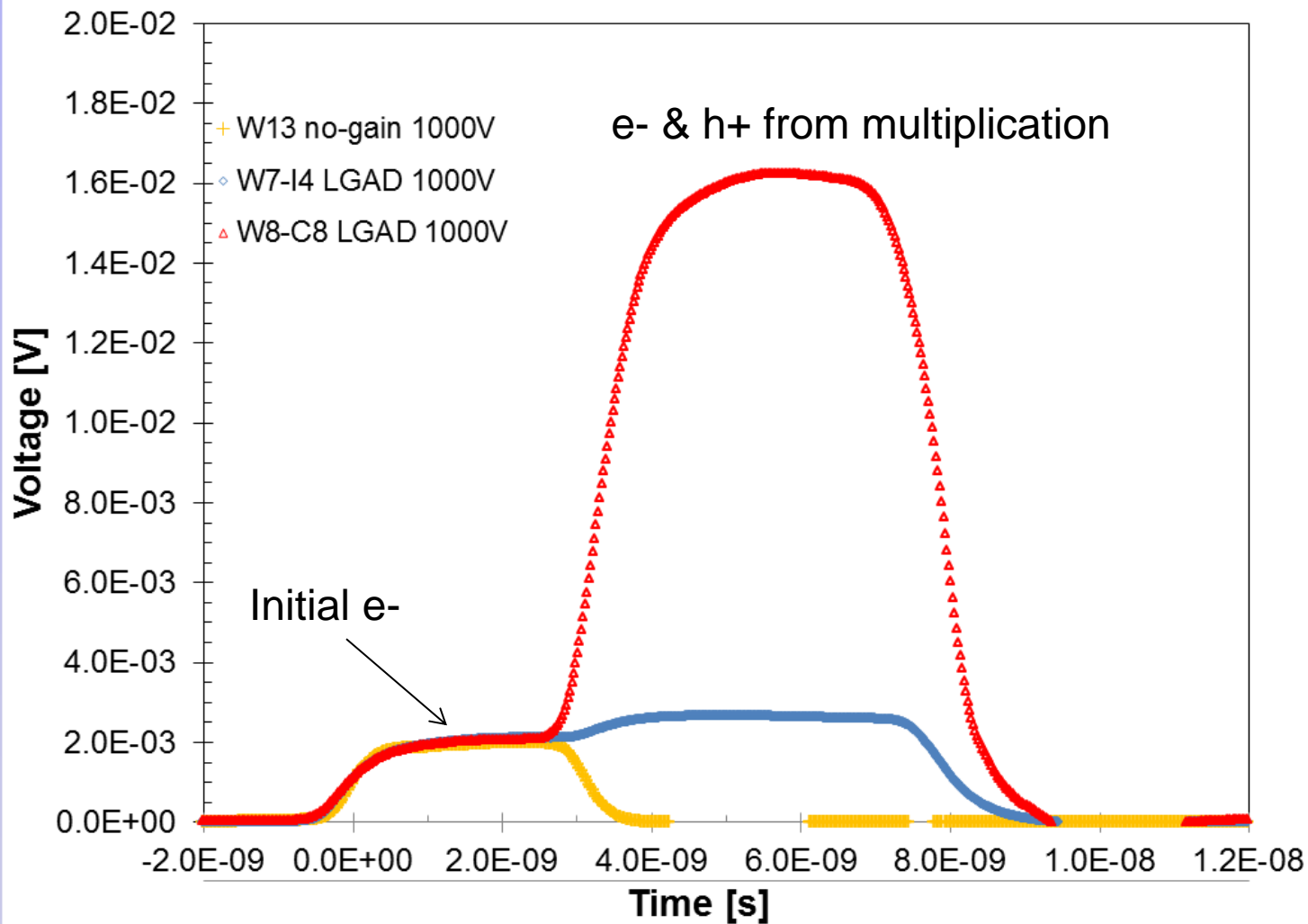


# High BW $\alpha$ TCT Set-up





# Pulse – shape analysis with $\alpha$ TCT

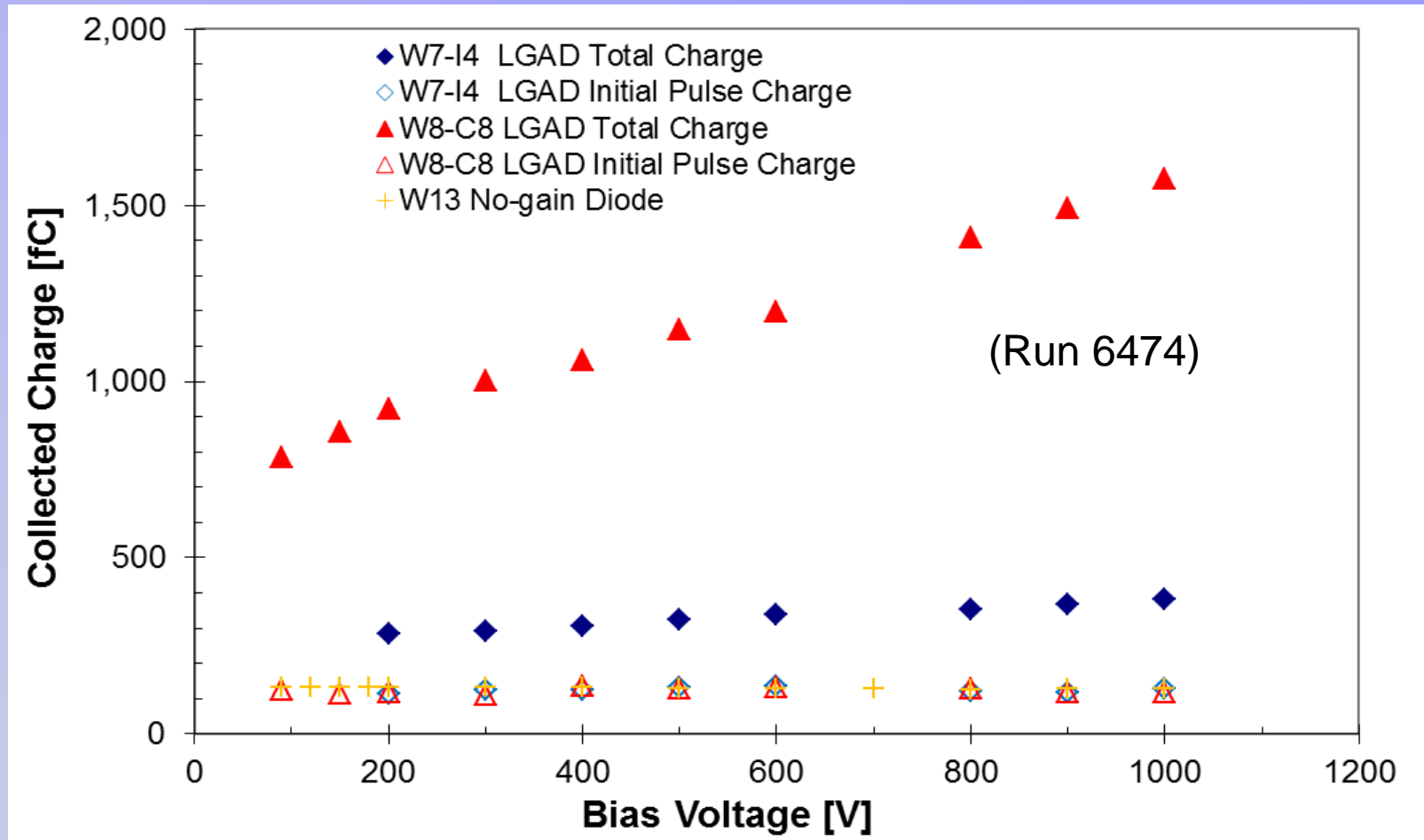


$$\text{Gain} = \text{Total pulse area} / \text{Initial Pulse Area}$$

Charge collection well described by simulations



# Total charge & initial Pulse charge



The initial pulse charge is identical for two different LGAD's (after correction) and a no-gain diode: Reflects the initial electron drift.

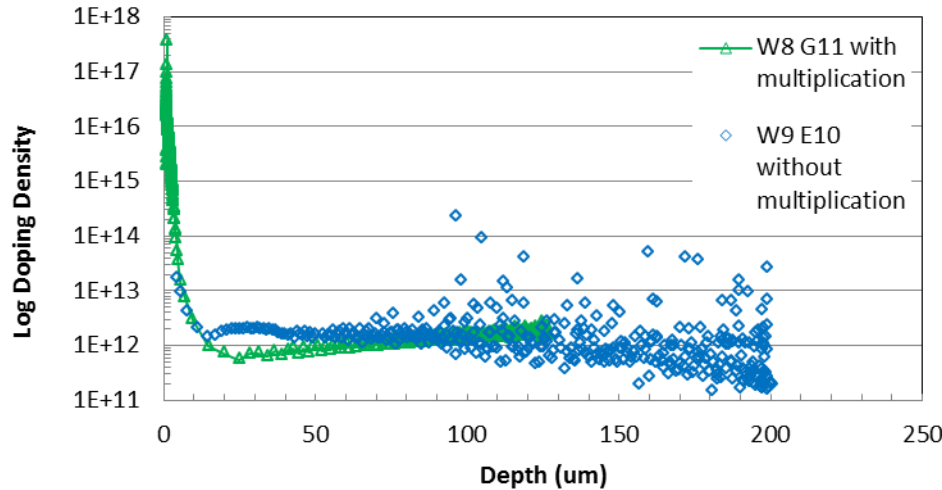
Large gain differences:  $G(W8-C8)/G(W7-I4) \approx 4$  at 1000V bias.

Original idea: correlation with high leakage current, turns out to be wrong



# Doping Density Profile N(x)

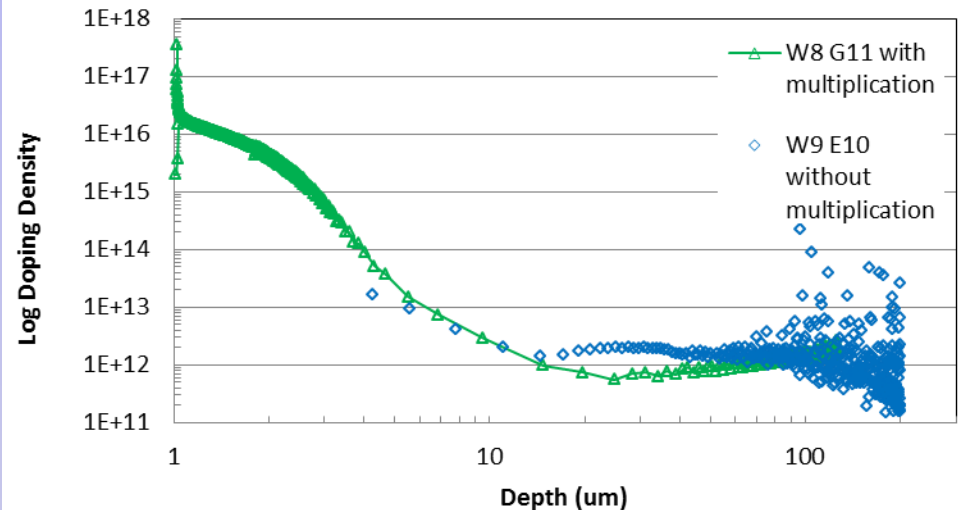
## Doping Density vs Depletion Depth



$$N = \frac{2}{\frac{d(1/C^2)}{dV}} \cdot \frac{1}{\epsilon q A^2}$$

**LGAD and no-gain diode have same doping profile far away from gain region!**

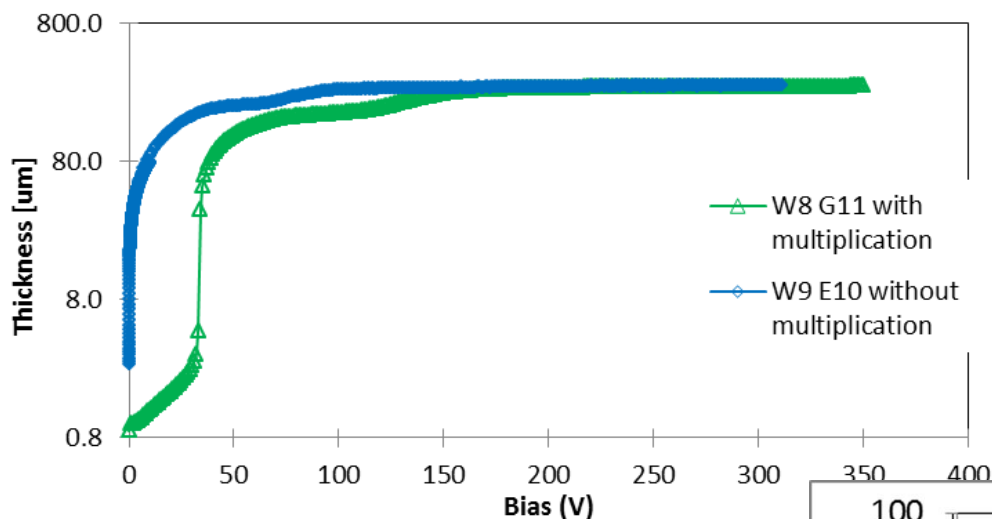
## Doping Density vs Depletion Depth





# Depleted thickness x vs. V

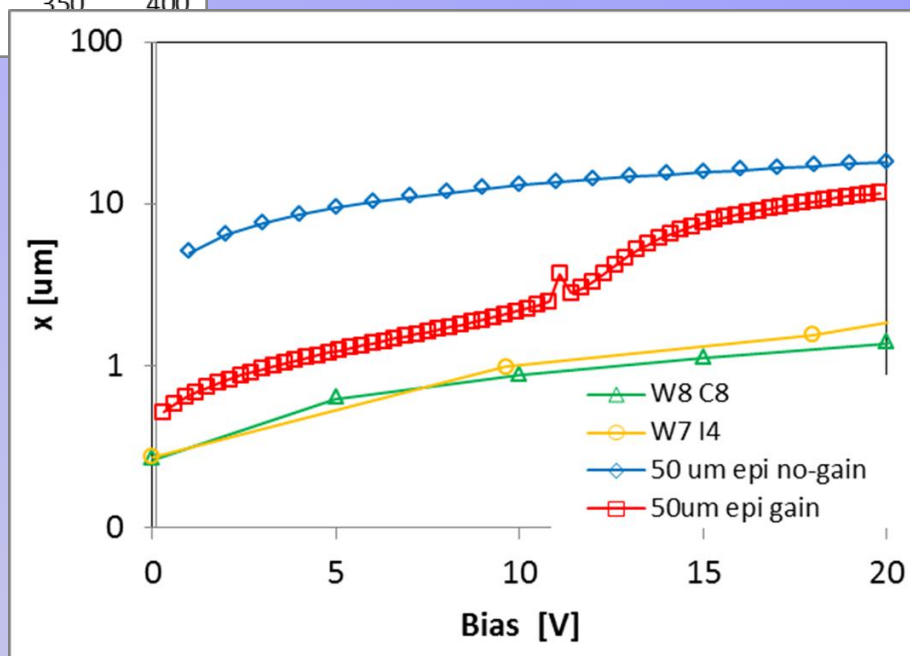
## Depleted Thickness vs. V



$$x = A / C$$

Conversion of  
capacitance  $C(V) \rightarrow C(x)$   
doping density  $N(V) \rightarrow N(x)$   
resistivity  $\rho(V) \rightarrow \rho(x)$

- Saturates at  $x \approx 250\mu\text{m}$  as expected
- Shows large voltage lag for LGAD





# Structure Screenshot

